

HVD135

Silicon Epitaxial Trench Pin Diode for Antenna Switching

HITACHI

ADE-208-948 (Z)
Rev.0
Jul. 2000

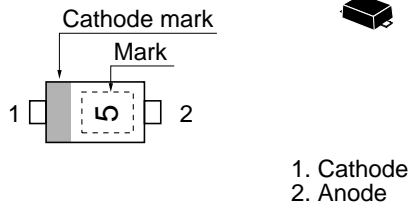
Features

- Adopting the trench structure improves low capacitance.(C = 0.6 pF max)
- Low forward resistance. (rf = 2.0 Ω max)
- Low operation current.
- Super small Flat Package (SFP) is suitable for surface mount design.

Ordering Information

Type No	Laser Mark	Package Code
HVD135	5	SFP

Outline



Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Item	Symbol	Value	Unit
Peak reverse voltage	V_{RM}	65	V
Reverse voltage	V_R	60	V
Forward current	I_F	100	mA
Power dissipation	P_d	150	mW
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

Electrical Characteristics ($T_a = 25^\circ\text{C}$)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I_R	—	—	0.1	μA	$V_R = 60\text{ V}$
Forward voltage	V_F	—	—	0.9	V	$I_F = 2\text{ mA}$
Capacitance	C	—	—	0.6	pF	$V_R = 1\text{ V}, f = 1\text{ MHz}$
Forward resistance	r_f	—	—	2.0	Ω	$I_F = 2\text{ mA}, f = 100\text{ MHz}$
ESD-Capability *1	—	100	—	—	V	C = 200 pF, R = 0 Ω , Both forward and reverse direction 1 pulse.

Notes : 1. Failure criterion ; $I_R > 100\text{ nA}$ at $V_R = 60\text{ V}$

2. Please do not use the soldering iron due to avoid high stress to the SFP package.

Main Characteristic

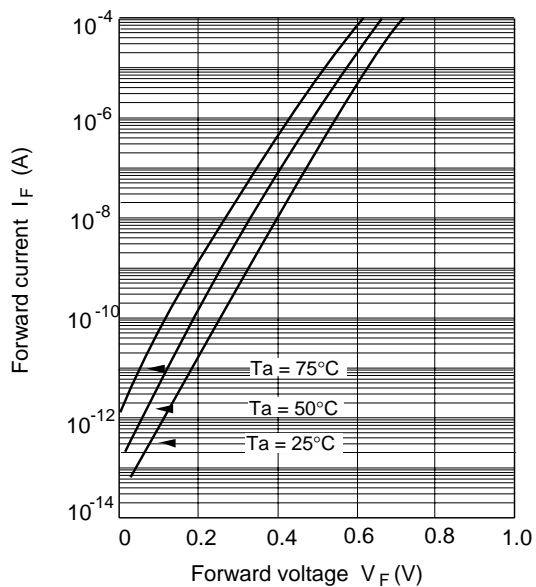


Fig.1 Forward current Vs. Forward voltage

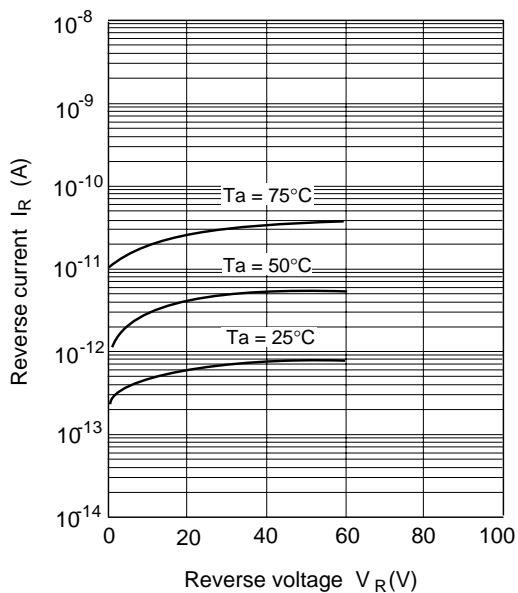


Fig.2 Reverse current Vs. Reverse voltage

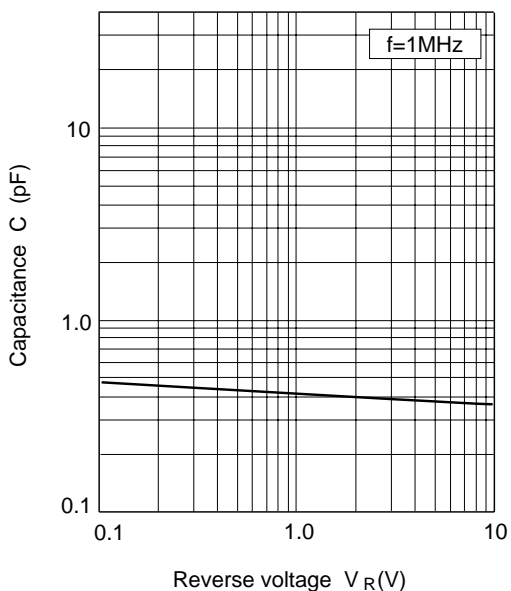


Fig.3 Capacitance Vs. Reverse voltage

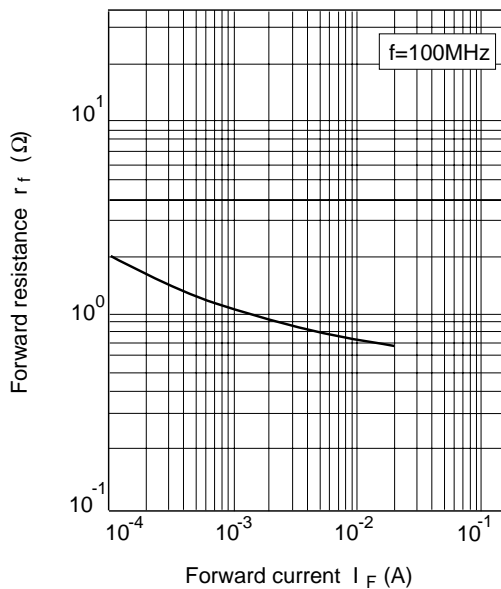


Fig.4 Forward resistance Vs. Forward current

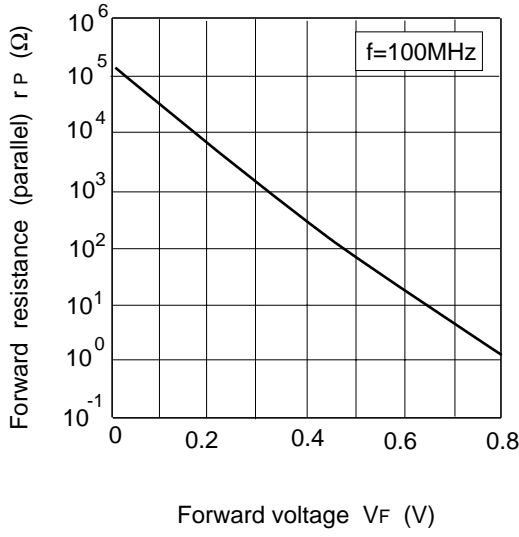
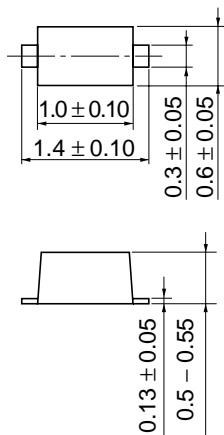


Fig.5 Forward resistance (parallel) Vs. Forward voltage

Package Dimensions

Unit: mm



Hitachi Code	SFP
JEDEC	—
EIAJ	—
Mass (reference value)	0.0010 g

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HITACHI**Hitachi, Ltd.**

Semiconductor & Integrated Circuits.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL NorthAmerica : <http://semiconductor.hitachi.com/>
 Europe : <http://www.hitachi-eu.com/hel/ecg>
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For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose, CA 95134
Tel: <1> (408) 433-1990
Fax: <1> (408) 433-0223

Hitachi Europe GmbH
Electronic Components Group
Dornacher Straße 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.
Electronic Components Group.
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 585160

Hitachi Asia Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 049318
Tel: 535-2100
Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3rd Flr, Hung Kuo Building, No.167,
Tun Hwa North Road, Taipei (105)
Taiwan
Tel: <886> (2) 2718-3666
Fax: <886> (2) 2718-8180
Telex: 23222 HAS-TP

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7th Flr, North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui,
Kowloon, Hong Kong
Tel: <852> (2) 735 9218
Fax: <852> (2) 730 0281
Telex: 40815 HITEC HX

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